

RADIO-FREQUENCY SWITCH HAVING REDISTRIBUTION LAYER INDUCTANCE

ABSTRACT

In some embodiments, a semiconductor chip device can include a semiconductor substrate having a switching circuit with a first node, and a plurality of layers configured to support the semiconductor substrate and to provide electrical connections for the switching circuit between a second node connectable to a location external to the semiconductor chip and the first node. The plurality of layers can include a redistribution layer, and a signal path can be implemented as a part of the redistribution layer. The signal path can have a first end electrically connected to the first node and a second end electrically connected to the second node, and be configured to provide a selected inductance.

[FIG.5A]